

Solid Tantalum Chip Capacitors 298D MICROTAN®, 298W Extended Range MICROTAN®, **Leadframeless Molded**





FEATURES

- Small sizes include 0603 and 0402 footprint
- Lead (Pb)-free L-shaped face-down terminations
- 8 mm tape and reel packaging available per EIA-481 and reeling per IEC 60286-3 7" [178 mm] standard
- · Mounting: surface mount
- · Material categorization: for definitions of compliance www.vishav.com/doc?99912 please



RoHS COMPLIANT **HALOGEN** FREE

GREEN (5-2008)

PERFORMANCE CHARACTERISTICS

www.vishav.com/doc?40169

Operating Temperature:

298D: -55 °C to +125 °C (above 85 °C, voltage derating is required)

298W: -55 °C to +125 °C

(above 40 °C, voltage derating is required)

Capacitance Range:

298D: 0.33 μF to 330 μF 298W: 2.2 µF to 220 µF

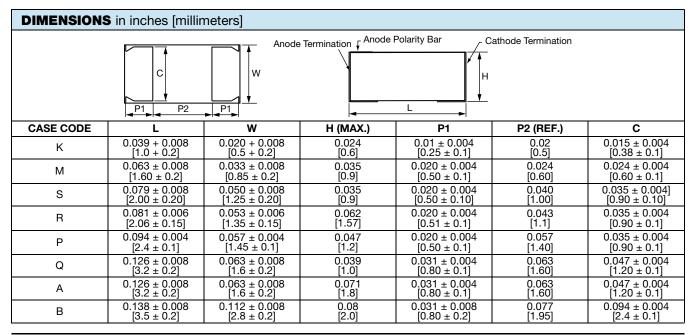
Capacitance Tolerance: ± 20 % standard, ± 10 % available

Voltage Range: 2.5 V_{DC} to 50 V_{DC}

ORDE	ERING INFORMA	ATION				
298D	335	X0	010	М	2	Т
TYPE 298D 298W	This is expressed in picofarads. The first two digits are the significant figures. The third is the number of zeros to follow.	CAPACITANCE TOLERANCE X0 = ± 20 % X9 = ± 10 %	This is expressed in volts. To complete the three-digit block, zeros precede the voltage rating. A decimal point is indicated by an "R" (6R3 = 6.3 V).	See Ratings and Case Codes table	TERMINATION 2 = 100 % tin 4 = gold plated	REEL SIZE AND PACKAGING T = tape and reel 7" [178 mm] reel

Note

Preferred tolerance and reel sizes are in bold. We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size. Voltage substitutions will be marked with the higher voltage rating.



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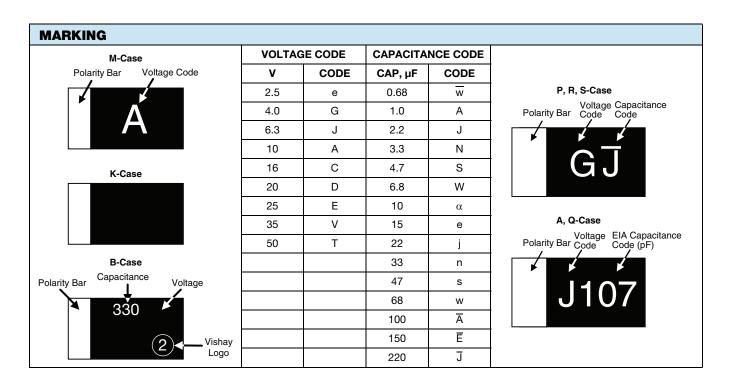


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RATII	RATINGS AND CASE CODES (298D, 298W Extended Range)												
μF	2.5 V	4 V		6.3 V		10	V	16 V	20 V	25 V	35 V	50 V	
	298D	298D	298W	298D	298W	298D	298W	298D	298W	298D	298D	298D	298D
0.33										K			
0.68										М	М		
1.0				K		K/M		K/M		S	M/R/S		Р
1.5						М							
2.2				K/M		K/M		М	K			Р	
3.3				М		М							
4.7		K		М		M/P	K	M/P		Р	Р		
10		K/M		M/S	K	М		R			Α		
15		K		М		М							
22	K	K/M		М		М							
33		М		М		Р	M ⁽¹⁾						
47	М	М		R/P/A	М	Р							
100		Р	М	P/A			Q						
220	Р	P/Q	Q										
330				В									

Note

(1) Preliminary values, contact factory for availability.





CAPACITANCE (µF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μΑ)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		2.5 V _{DC} AT	+85 °C; 1.6 V _{DC} A	AT +125 °C		
22	K	298D226X02R5K(2)T	10	40	20.00	0.027
47	М	298D476X02R5M(2)T	2.4	20	4.00	0.080
220	Р	298D227X02R5P(2)T	11	30	3.00	0.122
		4 V _{DC} AT +85 4 V _{DC} AT +40 °C; 2.5 V _L	5 °C; 2.7 V _{DC} AT +1 DC AT +85 °C; 1.6 \		298W	
4.7	К	298D475X0004K(2)T	0.5	15	20.00	0.027
10	K	298D106X0004K(2)T	4.0	50	20.00	0.027
10	М	298D106(1)004M(2)T	0.5	8	5.00	0.071
15	K	298D156X0004K(2)T	10	50	20.00	0.027
22	K	298D226X0004K(2)T	25	40	20.00	0.027
22	М	298D226X0004M(2)T	0.9	15	4.00	0.080
33	М	298D336X0004M(2)T	2.6	30	4.00	0.080
47	М	298D476X0004M(2)T	3.8	40	7.50	0.080
100	Р	298D107X0004P(2)T	4.0	30	2.00	0.100
100	М	298W107X0004M(2)T	110	60	15.00	0.041
220	Р	298D227(1)004P(2)T	17.6	30	3.00	0.122
220	Q	298D227X0004Q(2)T	88	80	15.00	0.061
220	Q	298W227X0004Q(2)T	88	80	15.00	0.061
		6.3 V _{DC} AT +8 6.3 V _{DC} AT +40 °C; 4.0 V	85 °C; 4 V _{DC} AT +1	25 °C - 298D Vpc AT +125 °C	- 298W	
1.0	K	298D105X06R3K(2)T	0.5	6	20.00	0.027
2.2	K	298D225X06R3K(2)T	0.5	8	20.00	0.027
2.2	М	298D225(1)6R3M(2)T	0.5	10	5.00	0.070
3.3	М	298D335(1)6R3M(2)T	0.5	8	6.00	0.090
4.7	М	298D475(1)6R3M(2)T	0.5	8	3.00	0.090
10	М	298D106X06R3M(2)T	0.6	8	5.00	0.071
10	S	298D106X06R3S(2)T	0.6	8	5.00	0.084
10	K	298W106X06R3K(2)T	10	30	15.00	0.032
15	М	298D156X06R3M(2)T	1.0	20	7.00	0.060
22	М	298D226X06R3M(2)T	2.8	20	5.50	0.067
33	М	298D336X06R3M(2)T	4.2	30	7.50	0.058
47	М	298W476X06R3M(2)T	29.6	45	10.00	0.050
47	R	298D476X06R3R(2)T	3.0	25	3.00	0.122
47	Р	298D476X06R3P(2)T	3.0	22	3.00	0.122
47	Α	298D476X06R3A(2)T	3.0	10	2.00	0.150
100	Р	298D107X06R3P(2)T	6.3	30	2.00	0.150
100	Α	298D107X06R3A(2)T	6.3	20	1.00	0.270
330	В	298D337X06R3B(2)T	64	50	3.00	0.412

[•] Part number definitions:

⁽¹⁾ Tolerance: for 10 % tolerance, specify "X9"; for 20 % tolerance, change to "X0"

⁽²⁾ Termination: for 100 % tin specify "2", for gold plated specify "4"

⁽¹⁾ Rating in development, contact factory for availability

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CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μΑ)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		10 V _{DC} AT +8 10 V _{DC} AT +40 °C; 6.3 V	35 °C; 7 V _{DC} AT +1 V _{DC} AT +85 °C; 4.0	25 °C - 298D V _{DC} AT +125 °C -	· 298W	
1.0	K	298D105X0010K(2)T	0.5	6	20.00	0.027
1.0	М	298D105(1)010M(2)T	0.5	6	12.00	0.045
1.5	М	298D155(1)010M(2)T	0.5	6	14.00	0.040
2.2	K	298D225X0010K(2)T	2.2	8	15.00	0.027
2.2	М	298D225X0010M(2)T	0.5	10	10.00	0.050
3.3	М	298D335(1)010M(2)T	0.5	8	6.00	0.090
4.7	K	298W475X0010K(2)T	10	50	50.00	0.017
4.7	М	298D475(1)010M(2)T	0.5	6	5.00	0.071
4.7	Р	298D475(1)010P(2)T	0.5	6	4.00	0.106
10	М	298D106X0010M(2)T	1.0	20	7.50	0.058
15	М	298D156X0010M(2)T	1.5	30	7.50	0.058
22	М	298D226X0010M(2)T	22	40	10.00	0.050
33	M ⁽¹⁾	298W336(1)010M(2)T	66	75	21.00	0.035
33	Р	298D336X0010P(2)T	3.3	20	4.00	0.150
47	Р	298D476X0010P(2)T	4.7	22	3.00	0.122
100	Q	298W107X0010Q(2)T	100	50	15.00	0.060
1.0	K	16 V _{DC} AT +8 16 V _{DC} AT +40 °C; 10 V 298D105X0016K(2)T	5 °C; 10 V _{DC} AT +1 DC AT +85 °C; 6.3 ° 1.6	125 °C - 298D V _{DC} AT +125 °C - 10	298W 20.00	0.027
1.0	М	298D105(1)016M(2)T	0.5	6	12.00	0.045
2.2	K	298W225(1)016K(2)T	10	50	50.00	0.017
2.2	М	298D225(1)016M(2)T	0.5	10	12.00	0.045
4.7	M	298D475X0016M(2)T	0.8	12	12.00	0.046
4.7	P	298D475(1)016P(2)T	0.8	6	4.00	0.106
10	r R	298D106(1)016R(2)T	1.6	8	8.00	0.075
10	n		Γ +85 °C; 13 V _{DC} A		8.00	0.075
0.33	K	298D334(1)020K(2)T	0.5	6	n/a	n/a
0.68	М	298D684(1)020M(2)T	0.5	6	20.00	0.042
1.0	S	298D105X0020S(2)T	0.5	6	10.00	0.059
4.7	Р	298D475(1)020P(2)T	1.0	6	4.00	0.106
			T +85 °C; 17 V _{DC} A	T +125 °C		
0.68	М	298D684(1)025M(2)T	0.5	6	20.00	0.042
1.0	М	298D105(1)025M(2)T	0.5	6	10.00	0.050
1.0	S	298D105X0025S(2)T	0.5	6	10.00	0.059
1.0	R	298D105(1)025R(2)T	0.5	6	10.00	0.067
4.7	Р	298D475(1)025P(2)T	1.2	6	4.00	0.106
10	Α	298D106X0025A(2)T	2.5	10	3.50	0.146
		35 V _{DC} A1	T +85 °C; 23 V _{DC} A	T +125 °C		
2.2	Р	298D225X0035P(2)T	0.8	8	8.00	0.075
		50 V _{DC} A1	T +85 °C; 33 V _{DC} A	T +125 °C		
1.0	Р	298D105X0050P(2)T	0.5	8	8.00	0.075

Part number definitions:

⁽¹⁾ Tolerance: for 10 % tolerance, specify "X9"; for 20 % tolerance, change to "X0"

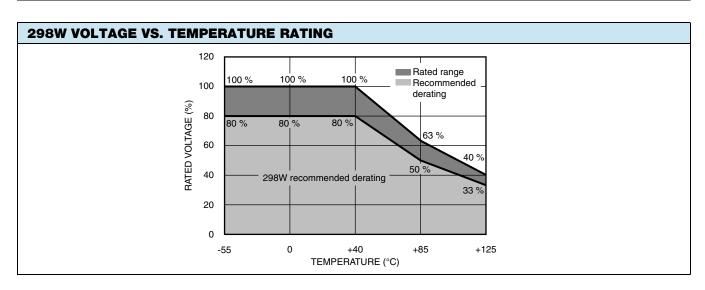
⁽²⁾ Termination: for 100 % tin specify "2", for gold plated specify "4"

⁽¹⁾ Rating in development, contact factory for availability



RECOMMENDED VOLTAGE DERATING (298D)					
+85 °C RATING	+125 °C RATING				
WORKING VOLTAGE (V)	WORKING VOLTAGE (V)				
2	1.3				
4	2.7				
6.3	4				
10	7				
15	10				
16	10				
20	13				
25	17				
35	23				
50	33				

RECOMMENDED VOLTAGE DERATING (298W)						
-55 °C/+40 °C RATING	+40 °C/+85 °C RATING	+85 °C/+125 °C RATING				
RATED VOLTAGE (V)	CATEGORY VOLTAGE (V)	CATEGORY VOLTAGE (V)				
4	2.5	1.6				
6.3	4	2.5				
10	6.3	4				
16	10	6.3				
20	13	8				
25	17	10				
35	23	14				





STANDARD PACKAGING QUANTITY				
CASE CODE	QUANTITY (pcs/reel)			
CASE CODE	7" REEL			
К	5000			
M	4000			
S	3000			
R	2500			
P	3000			
Q	2500			
A	2000			
В	2000			

POWER DISSIPATION					
CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT +25 °C (W) IN FREE AIR				
К	0.015				
M	0.025				
S	0.035				
R	0.045				
Р	0.045				
Q	0.055				
A	0.075				
В	0.085				

PRODUCT INFORMATION				
Micro Guide				
Pad Dimensions	www.vishay.com/doc?40115			
Packaging Dimensions				
Moisture Sensitivity	www.vishay.com/doc?40135			
Typical Performance Characteristics	www.vishay.com/doc?40169			
SELECTOR GUIDES				
Solid Tantalum Selector Guide	www.vishay.com/doc?49053			
Solid Tantalum Chip Capacitors	www.vishay.com/doc?40091			
FAQ				
Frequently Asked Questions	www.vishay.com/doc?40110			

Guide for Leadframeless Molded Tantalum Capacitors

INTRODUCTION

Tantalum electrolytic capacitors are the preferred choice in applications where volumetric efficiency, stable electrical parameters, high reliability, and long service life are primary considerations. The stability and resistance to elevated temperatures of the tantalum / tantalum oxide / manganese dioxide system make solid tantalum capacitors an appropriate choice for today's surface mount assembly technology.

Vishay Sprague has been a pioneer and leader in this field, producing a large variety of tantalum capacitor types for consumer, industrial, automotive, military, and aerospace electronic applications.

Tantalum is not found in its pure state. Rather, it is commonly found in a number of oxide minerals, often in combination with Columbium ore. This combination is known as "tantalite" when its contents are more than one-half tantalum. Important sources of tantalite include Australia, Brazil, Canada, China, and several African countries. Synthetic tantalite concentrates produced from tin slags in Thailand, Malaysia, and Brazil are also a significant raw material for tantalum production.

Electronic applications, and particularly capacitors, consume the largest share of world tantalum production. Other important applications for tantalum include cutting tools (tantalum carbide), high temperature super alloys, chemical processing equipment, medical implants, and military ordnance.

Vishay Sprague is a major user of tantalum materials in the form of powder and wire for capacitor elements and rod and sheet for high temperature vacuum processing.

THE BASICS OF TANTALUM CAPACITORS

Most metals form crystalline oxides which are non-protecting, such as rust on iron or black oxide on copper. A few metals form dense, stable, tightly adhering, electrically insulating oxides. These are the so-called "valve" metals and include titanium, zirconium, niobium, tantalum, hafnium, and aluminum. Only a few of these permit the accurate control of oxide thickness by electrochemical means. Of these, the most valuable for the electronics industry are aluminum and tantalum.

Capacitors are basic to all kinds of electrical equipment, from radios and television sets to missile controls and automobile ignitions. Their function is to store an electrical charge for later use.

Capacitors consist of two conducting surfaces, usually metal plates, whose function is to conduct electricity. They are separated by an insulating material or dielectric. The dielectric used in all tantalum electrolytic capacitors is tantalum pentoxide.

Tantalum pentoxide compound possesses high-dielectric strength and a high-dielectric constant. As capacitors are being manufactured, a film of tantalum pentoxide is applied to their electrodes by means of an electrolytic process. The film is applied in various thicknesses and at various voltages and although transparent to begin with, it takes on different colors as light refracts through it. This coloring occurs on the tantalum electrodes of all types of tantalum capacitors.

Rating for rating, tantalum capacitors tend to have as much as three times better capacitance / volume efficiency than aluminum electrolytic capacitors. An approximation of the capacitance / volume efficiency of other types of capacitors may be inferred from the following table, which shows the dielectric constant ranges of the various materials used in each type. Note that tantalum pentoxide has a dielectric constant of 26, some three times greater than that of aluminum oxide. This, in addition to the fact that extremely thin films can be deposited during the electrolytic process mentioned earlier, makes the tantalum capacitor extremely efficient with respect to the number of microfarads available per unit volume. The capacitance of any capacitor is determined by the surface area of the two conducting plates, the distance between the plates, and the dielectric constant of the insulating material between the plates.

COMPARISON OF CAPACITOR DIELECTRIC CONSTANTS				
DIELECTRIC	e DIELECTRIC CONSTANT			
Air or Vacuum	1.0			
Paper	2.0 to 6.0			
Plastic	2.1 to 6.0			
Mineral Oil	2.2 to 2.3			
Silicone Oil	2.7 to 2.8			
Quartz	3.8 to 4.4			
Glass	4.8 to 8.0			
Porcelain	5.1 to 5.9			
Mica	5.4 to 8.7			
Aluminum Oxide	8.4			
Tantalum Pentoxide	26			
Ceramic	12 to 400K			

In the tantalum electrolytic capacitor, the distance between the plates is very small since it is only the thickness of the tantalum pentoxide film. As the dielectric constant of the tantalum pentoxide is high, the capacitance of a tantalum capacitor is high if the area of the plates is large:

$$C = \frac{eA}{t}$$

where

C = capacitance

e = dielectric constant

A = surface area of the dielectric

t = thickness of the dielectric

Tantalum capacitors contain either liquid or solid electrolytes. In solid electrolyte capacitors, a dry material (manganese dioxide) forms the cathode plate. A tantalum lead is embedded in or welded to the pellet, which is in turn connected to a termination or lead wire. The drawings show the construction details of the surface mount types of tantalum capacitors shown in this catalog.

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SOLID ELECTROLYTE TANTALUM CAPACITORS

Solid electrolyte capacitors contain manganese dioxide, which is formed on the tantalum pentoxide dielectric layer by impregnating the pellet with a solution of manganous nitrate. The pellet is then heated in an oven, and the manganous nitrate is converted to manganese dioxide.

The pellet is next coated with graphite, followed by a layer of metallic silver, which provides a conductive surface between the pellet and the leadframe.

Molded chip tantalum capacitor encases the element in plastic resins, such as epoxy materials. After assembly, the capacitors are tested and inspected to assure long life and reliability. It offers excellent reliability and high stability for consumer and commercial electronics with the added feature of low cost.

Surface mount designs of "Solid Tantalum" capacitors use lead frames or lead frameless designs as shown in the accompanying drawings.

TANTALUM CAPACITORS FOR ALL DESIGN CONSIDERATIONS

Solid electrolyte designs are the least expensive for a given rating and are used in many applications where their very small size for a given unit of capacitance is of importance. They will typically withstand up to about 10 % of the rated DC working voltage in a reverse direction. Also important are their good low temperature performance characteristics and freedom from corrosive electrolytes.

Vishay Sprague patented the original solid electrolyte capacitors and was the first to market them in 1956. Vishay Sprague has the broadest line of tantalum capacitors and has continued its position of leadership in this field. Data sheets covering the various types and styles of Vishay Sprague capacitors for consumer and entertainment electronics, industry, and military applications are available where detailed performance characteristics must be specified.

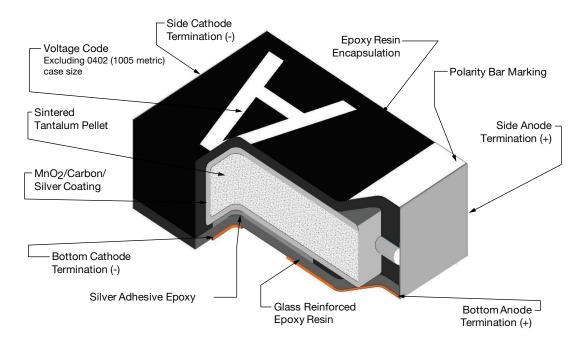


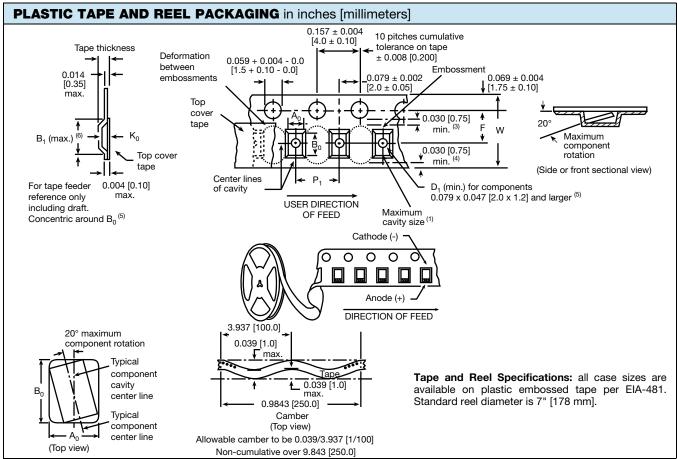
Fig. 1 - Leadframeless Molded Capacitors, All Types



SOLID TANTALUM CAPACITORS - LEADFRAMELESS MOLDED							
SERIES	TL8	298D	298W	TR8			
PRODUCT IMAGE	9	9	9	9			
TYPE		Solid tantalum leadframele	ess molded chip capacitors				
	Small size including 0603 and 0402 foot print						
FEATURES	Ultra low profile	Industrial grade	Industrial grade, extended range	Low ESR			
TEMPERATURE RANGE	Operating Temperature: -55 °C to +125 °C (above 40 °C, voltage derating is required)	Operating Temperature: -55 °C to +125 °C (above 85 °C, voltage derating is required)	Operating Temperature: -55 °C to +125 °C (above 40 °C, voltage derating is required)	Operating Temperature: -55 °C to +125 °C (above 85 °C, voltage derating is required)			
CAPACITANCE RANGE	0.68 μF to 220 μF	0.68 μF to 330 μF	2.2 μF to 220 μF	1 μF to 330 μF			
VOLTAGE RANGE	4 V to 35 V	2.5 V to 50 V	4 V to 16 V	2.5 V to 25 V			
CAPACITANCE TOLERANCE	APACITANCE TOLERANCE ± 20 %, ± 10 %						
DISSIPATION FACTOR	6 % to 80 %	6 % to 80 %	30 % to 80 %	6 % to 80 %			
CASE CODES	W0, W9, A0, B0	K, M, R, P, Q, A, S, B	K, M, Q	M, R, P, Q, A, B			
TERMINATION	100 % tin		100 % tin or gold plated				

SOLID TANTALUM CAPACITORS - LEADFRAMELESS MOLDED							
SERIES	TP8 TM8 DLA 11020			T42			
PRODUCT IMAGE	9	96	96				
TYPE	Solid tantalum leadframeless molded chip capacitors						
FEATURES	Small siz	Built in fuse, double-stacked					
FEATURES	High performance, automotive grade	High reliability	High reliability, DLA approved	High reliability, ultra-low ESR			
TEMPERATURE RANGE	-55	Operating T o °C to +125 °C (above 85 °C	emperature: C, voltage derating is requi	red)			
CAPACITANCE RANGE	1 μF to 100 μF	0.68 μF to 47 μF	1 μF to 47 μF	10 μF to 470 μF			
VOLTAGE RANGE	6.3 V to 40 V	2 V to 40 V	6.3 V to 40 V	16 V to 75 V			
CAPACITANCE TOLERANCE	± 20 %, ± 10 %						
DISSIPATION FACTOR	6 % to 30 %	6 % to 20 %	6 % to 8 %	6 % to 15 %			
CASE CODES	M, W, R, P, A, N, T, B	K, M, W, R, P, A, N, T	M, W, R, P, A, N, T	M2			
TERMINATION	100 % tin	Tin / lead solder plated or 100 % tin	Tin / lead solder plated or gold plated	Tin / lead solder plated or 100 % tin			





Notes

- Metric dimensions will govern. Dimensions in inches are rounded and for reference only.
- A₀, B₀, K₀, are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀, K₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the components within the cavity of not more than 20°.

 Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "B" minimum trailer and the state of the component of the component within the cavity of not more than 20°.
- "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum.
- This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less.
- This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less.
- The embossed hole location shall be measured from the sprocket hole controlling the location of the embossement. Dimensions of embossement location shall be applied independent of each other.
- B₁ dimension is a reference dimension tape feeder clearance only.

CARRIER TA	APE DIMENS	SIONS in inche	s [millimeters]	FOR 298D,	298W, TR8,	TP8, TL8	
CASE CODE	TAPE SIZE	B ₁ (MAX.) ⁽¹⁾	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	W
M ⁽²⁾	8 mm	0.075 [1.91]	0.02 [0.5]	0.138 [3.5]	0.043 [1.10]	0.157 [4.0]	0.315 [8.0]
W	8 mm	0.112 [2.85]	0.039 [1.0]	0.138 [3.5]	0.053 [1.35]	0.157 [4.0]	0.315 [8.0]
R	8 mm	0.098 [2.46]	0.039 [1.0]	0.138 [3.5]	0.066 [1.71]	0.157 [4.0]	0.315 [8.0]
Р	8 mm	0.108 [2.75]	0.02 [0.5]	0.138 [3.5]	0.054 [1.37]	0.157 [4.0]	0.315 [8.0]
Α	8 mm	0.153 [3.90]	0.039 [1.0]	0.138 [3.5]	0.078 [2.00]	0.157 [4.0]	0.315 [8.0]
A0, Q	8 mm	-	0.02 [0.5]	0.138 [3.5]	0.049 [1.25]	0.157 [4.0]	0.315 [8.0]
В	8 mm	0.157 [4.0]	0.039 [1.0]	0.138 [3.5]	0.087[2.22]	0.157 [4.0]	0.315 [8.0]
W0	8 mm	0.094 [2.40]	0.029 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.315 [8.0]
W9, S	8 mm	0.126 [3.20]	0.029 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.315 [8.0]
B0	12 mm	0.181 [4.61]	0.059 [1.5]	0.217 [5.5]	0.049 [1.25]	0.157 [4.0]	0.472 [12.0]

- (1) For reference only
- (2) Packaging of M case in plastic tape is available per request



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CARRIER TAPE DIMENSIONS in inches [millimeters] FOR TM8							
CASE CODE	TAPE SIZE	B ₁ (MAX.) ⁽¹⁾	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	W
М	8 mm	0.075 [1.91]	0.02 [0.5]	0.138 [3.5]	0.043 [1.10]	0.157 [4.0]	0.315 [8.0]
W	8 mm	0.112 [2.85]	0.039 [1.0]	0.138 [3.5]	0.053 [1.35]	0.157 [4.0]	0.315 [8.0]
R	8 mm	0.098 [2.46]	0.039 [1.0]	0.138 [3.5]	0.066 [1.71]	0.157 [4.0]	0.315 [8.0]
Р	8 mm	0.108 [2.75]	0.02 [0.5]	0.138 [3.5]	0.054 [1.37]	0.157 [4.0]	0.315 [8.0]
Α	8 mm	0.153 [3.90]	0.039 [1.0]	0.138 [3.5]	0.078 [2.00]	0.157 [4.0]	0.315 [8.0]
N	12 mm	0.154 [3.90]	0.059 [1.5]	0.216 [5.5]	0.051 [1.30]	0.157 [4.0]	0.472 [12.0]
Т	12 mm	0.154 [3.90]	0.059 [1.5]	0.216 [5.5]	0.067 [1.70]	0.157 [4.0]	0.472 [12.0]

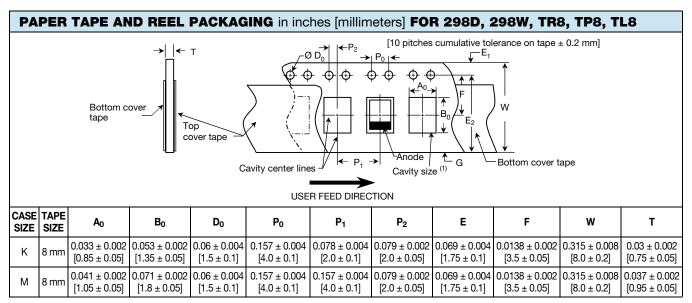
Notes

(1) For reference only

CARRIER TAPE DIMENSIONS in inches [millimeters] FOR T42							
CASE CODE	TAPE SIZE	B ₁ (MAX.) ⁽¹⁾	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	w
M2	16 mm	0.404 [10.3]	0.059 [1.5]	0.295 [7.5]	0.176 [4.5]	0.472 [12.0]	0.630 [16.0]

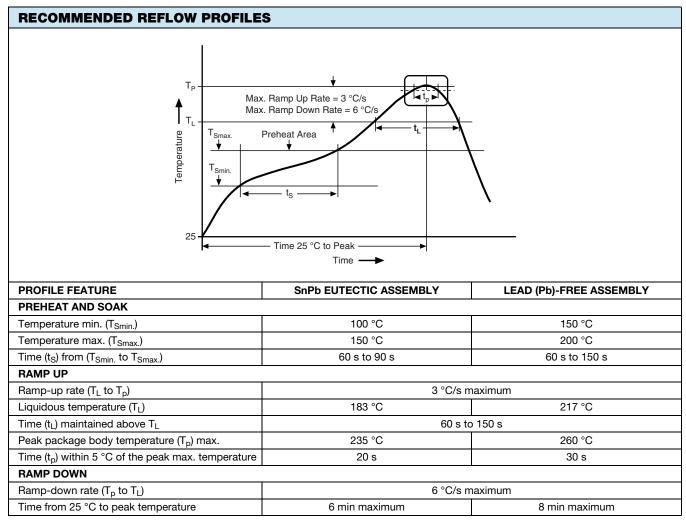
Note

(1) For reference only



Note

(1) A₀, B₀ are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°.

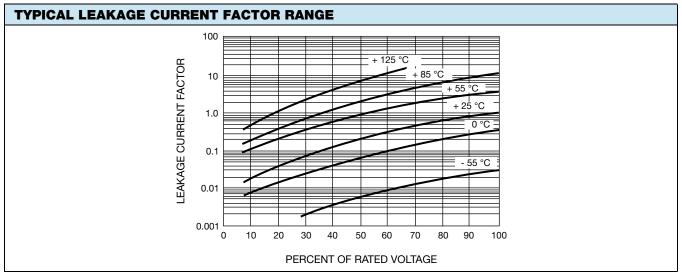


Note

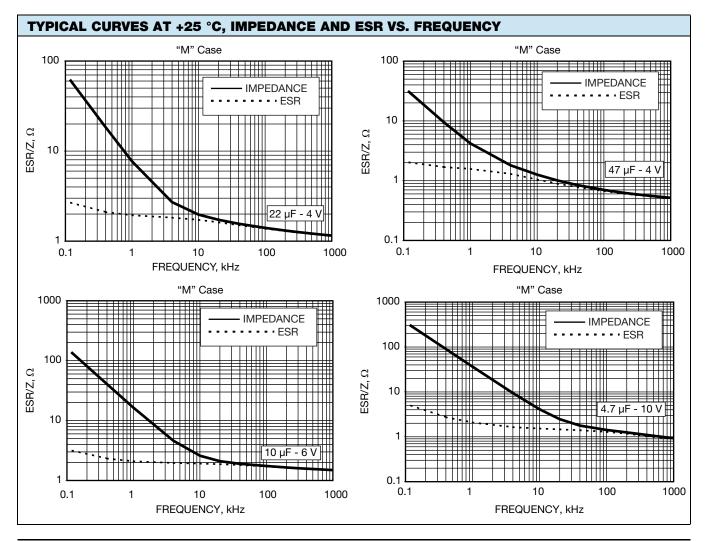
• Capacitors should withstand reflow profile as per J-STD-020 standard

PAD DIMENSIONS in inches [millimeters]					
CASE CODE	A (MIN.)	B (NOM.)	C (NOM.)	D (NOM.)	
K	0.028 [0.70]	0.018 [0.45]	0.024 [0.60]	0.059 [1.50]	
М	0.039 [1.00]	0.028 [0.70]	0.024 [0.60]	0.080 [2.00]	
R, W, W0, W9, S	0.059 [1.50]	0.031 [0.80]	0.039 [1.00]	0.102 [2.60]	
Р	0.063 [1.60]	0.031 [0.80]	0.047 [1.20]	0.110 [2.80]	
A, Q, A0	0.071 [1.80]	0.067 [1.70]	0.053 [1.35]	0.187 [4.75]	
B, B0, N, T	0.118 [3.00]	0.071 [1.80]	0.065 [1.65]	0.207 [5.25]	
M2	0.315 [8.00]	0.098 [2.50]	0.197 [5.00]	0.394 [10.0]	

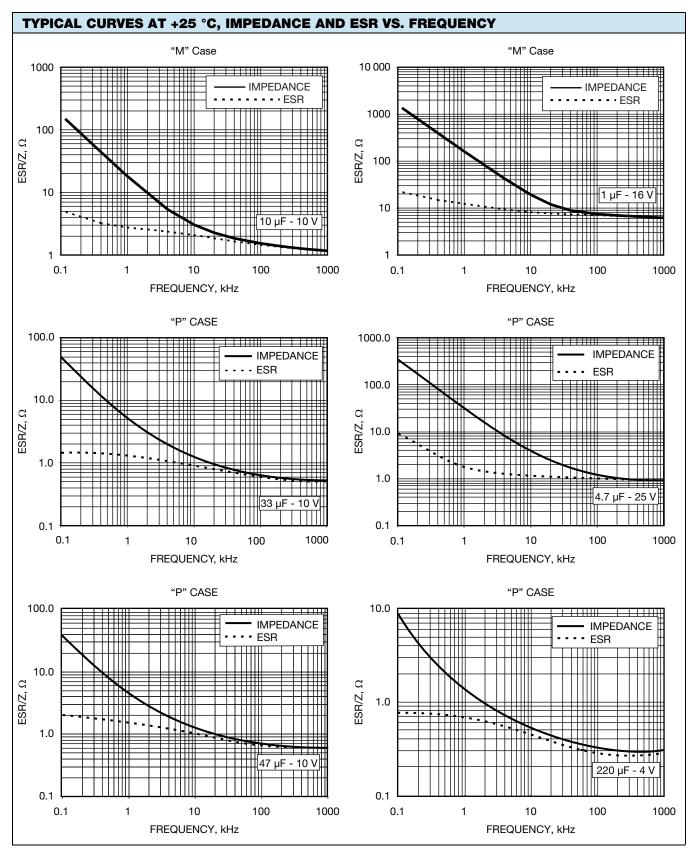




- At +25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table
- At +85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table
- At +125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table







Vishay Sprague

GUIDE TO APPLICATION

 AC Ripple Current: the maximum allowable ripple current shall be determined from the formula:

$$I_{RMS} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = power dissipation in watts at +25 °C (see paragraph number 5 and the table Power Dissipation as given in the tables in the product datasheets)

R_{ESR} = the capacitor equivalent series resistance at the specified frequency

2. **AC Ripple Voltage:** the maximum allowable ripple voltage shall be determined from the formula:

$$V_{\text{RMS}} = Z \sqrt{\frac{P}{R_{\text{ESR}}}}$$

or, from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

where,

P = power dissipation in watts at +25 °C (see paragraph number 5 and the table Power Dissipation as given in the tables in the product datasheets)

R_{ESR} = the capacitor equivalent series resistance at the specified frequency

Z = the capacitor impedance at the specified frequency

- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at +25 °C.
- 3. **Reverse Voltage:** these capacitors are capable of withstanding peak voltages in the reverse direction equal to 10 % of the DC rating at +25 °C, 5 % of the DC rating at +25 °C, 5 % of the DC rating at +85 °C, and 1 % of the DC rating at +125 °C.
- 4. **Temperature Derating:** if these capacitors are to be operated at temperatures above +25 °C, the permissible RMS ripple current shall be calculated using the derating factors as shown:

TEMPERATURE	DERATING FACTOR
+25 °C	1.0
+85 °C	0.9
+125 °C	0.4

5. Power Dissipation: power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_{RMS} value be established when calculating permissible operating levels. (Power Dissipation calculated using +25 °C temperature rise.)

- 6. **Printed Circuit Board Materials:** molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelanized steel).
- 7. Attachment:
- 7.1 **Solder Paste:** the recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.
- 7.2 **Soldering:** capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering and hot plate methods. The Soldering Profile charts show recommended time / temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 2 °C per s. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.
- 7.2.1 Backward and Forward Compatibility: capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.
- 8. Cleaning (Flux Removal) After Soldering: molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC / ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.
- 8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. DO NOT EXCEED 9W/I at 40 kHz for 2 min.
- 9. Recommended Mounting Pad Geometries: proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and / or circuit board design.



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